

Reliability testing starts with *reliable sockets*

Snap Fit Technology

Molded components ready for custom fit and assembly.



- ✓ Flexible socket designs - > *reduced cost and lead-time*
- ✓ Integrated socket solutions -> *reduced risk*
- ✓ In-house tool and mold -> *rapid response and turnaround*
- ✓ Extensive catalog -> *easy purchase*

MECHANICAL PROPERTIES

Pitch: LGA/QFN: 0.30mm – 1.00mm

BGA PACKAGE SIZE MIN: 0.50mm X 0.50mm
MAX: 4.0mm X 4.0mm

Pin Count: 64 pin max

Contact Force: 15.3gf (H033)

Temperature: -55°C to +150°C

Socket Dimensions: W – 20.0mm
L – 16.50mm
H – 13.94mm

ELECTRICAL PROPERTIES

Contact Resistance: <35 mΩ

Current Rating: >0.50 amp

Bandwidth @ -1dB: up to 15.7 GHz

MATERIALS

Stamped Contact: BeCu, Au Plate

Contact Spring SS, Au Plate

Plastic Ultem

Socket Hardware SS

Part Numbering System

